Wafer Flux WS-3401-A

Features
- Water-soluble
- Viscosity suitable for 150–300 mm wafers as a damming flux
- No residue after multiple reflow/cleaning cycles
- Uniform bump shape
- Halogen-free
- Suitable for SnPb and Pb-free, and high temperature applications
- Non-corrosive to underbump metallization

Introduction
Wafer Flux WS-3401-A is a high viscosity semiconductor-grade flux, specifically optimized as a damming flux for the edge of the wafer and to prevent backside contamination. Working with the natural surface tension of solder, WS-3401-A produces uniform hemispherical bumps without solder-robbing or solder-bridging.

Properties

<table>
<thead>
<tr>
<th>Property</th>
<th>Value</th>
<th>Test Method</th>
</tr>
</thead>
<tbody>
<tr>
<td>Flux Type</td>
<td>M0</td>
<td>J-STD-004/IPC-TM-650: 2.3.32 and 2.3.33</td>
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<tr>
<td>Classification:</td>
<td></td>
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<tr>
<td>Typical Viscosity:</td>
<td>1.5Kcps (peak)</td>
<td>Brookfield HB DVII + CP</td>
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<tr>
<td>SIR (Ohms, post cleaning):</td>
<td>Pass (&gt;109 after 7 days @85°C and 85% RH)</td>
<td>J-STD-004 (IPC-TM-650: 2.6.33 IPC-B-24)</td>
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<tr>
<td>Typical Acid Value:</td>
<td>81mg KOH/g</td>
<td>Titration</td>
</tr>
<tr>
<td>Specific Gravity:</td>
<td>1.08g/cc</td>
<td>J-STD-004B</td>
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<tr>
<td>Color:</td>
<td>Deep Amber to Light Brown</td>
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<tr>
<td>Shelf Life:</td>
<td>6 months</td>
<td>0°C to +25°C</td>
</tr>
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</table>

All information is for reference only. Not to be used as incoming product specifications.

Application
WS-3401-A can be applied by standard spin-coating techniques, but may be too viscous for many applications. For copper pillar applications, WS-3401-A is used (in conjunction with WS-3401) as a damming flux around the edge of the wafer, to prevent backside contamination.

Cleaning
WS-3401-A is designed to be cleaned with DI water or water with an added cleaner. Ideal conditions for spray cleaning are 25 °C or higher for >1 minute at >60psi.

Packaging
Wafer Flux WS-3401-A is available in containers from 100g to 3.2kg (1 gallon). Other packaging can be provided to meet specific requirements.

Storage
WS-3401-A containers should be stored at 0°C to 25°C for maximum shelf life. Storage temperatures should not exceed 25 °C for more than 4 days, and should never exceed 30 °C. After removing from cold storage, WS-3401-A should be allowed to stand for at least 4 hours at room temperature before using.
Technological Support
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation’s team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

Material Safety Data Sheets
The MSDS for this product can be found online at: http://www.indium.com/msds

Wafer Flux WS-3401-A

Reflow

Recommended Profile:

The above profile is recommended as a starting point for 300mm wafers with SnAg solder microbumps, and should be optimized by the user to meet their individual process needs. Wafers should be reflowed in a nitrogen atmosphere (<10ppm O₂ is recommended, but <20ppm O₂ may be feasible; however, results may not be optimal). Note that bridging or solder thieving may be seen for fine pitch microbumps (<60microns) on copper pillars, and that reducing the peak temperature will reduce the occurrence of this failure mode.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.